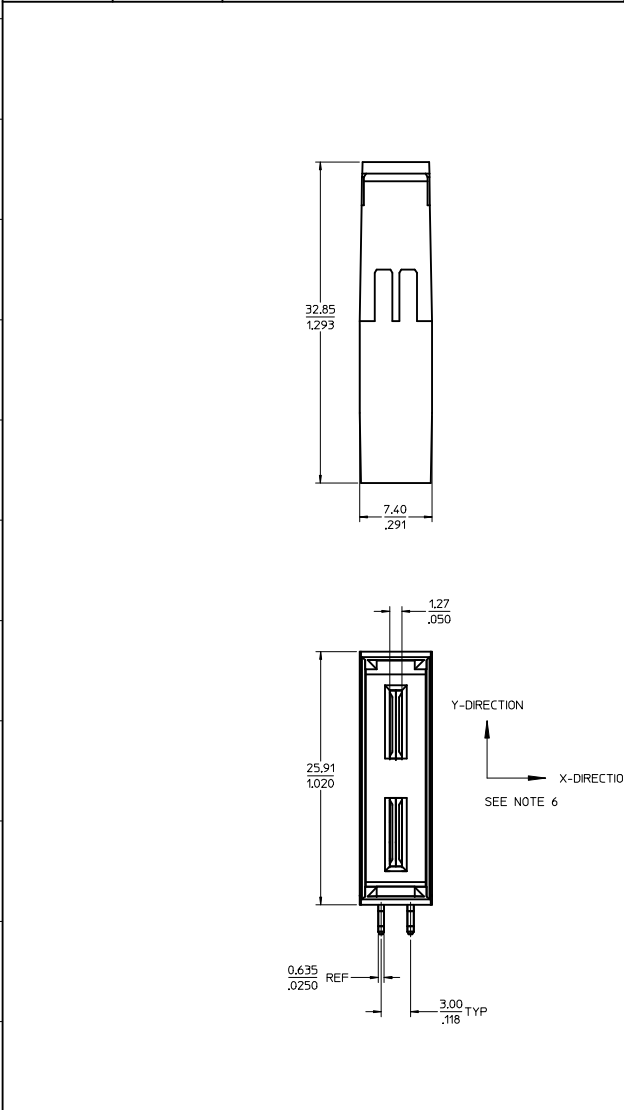
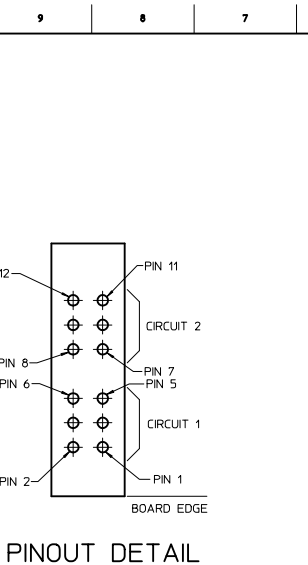
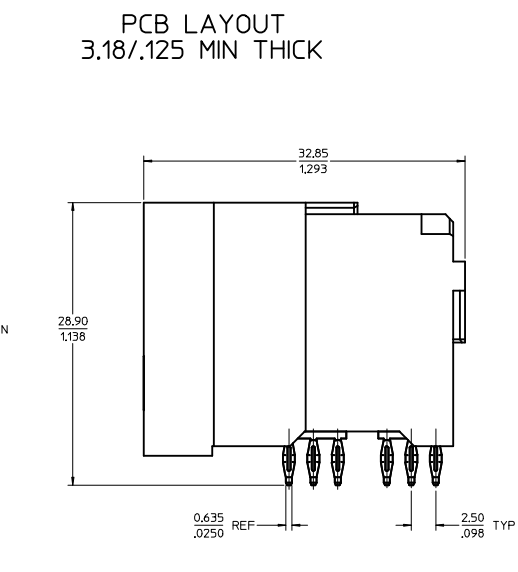
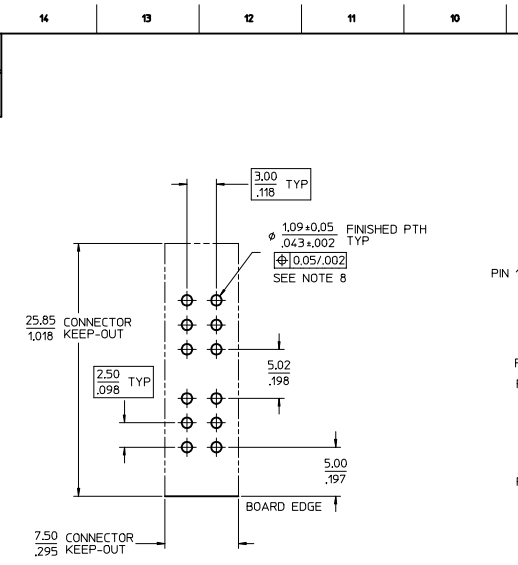


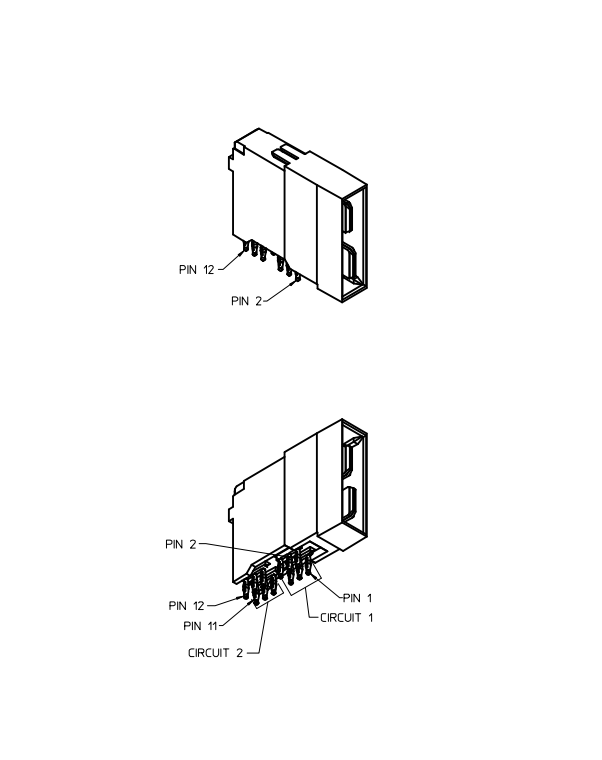
PART NUMBER	TAIL PLATING	PLATING
75561-6000	TIN	0.754µm/304µm MIN SELECT HARD GOLD IN CONTACT AREA WITH 2.504µm/1004µm MIN SELECT TIN IN TAIL AREA OVER 1.254µm/504µm MIN NICKEL OVERALL



REFERENCE DOCUMENTS	
PS-75431-999	PRODUCT SPECIFICATION: PERFORMANCE AND RATINGS
SD-75555-***	FINAL ASSEMBLY CONFIGURATION DRAWING



- NOTES:
1. MATERIALS:
- HOUSING: 30% GLASS FILLED, LCP 94V-0, COLOR: BLACK
- TERMINALS: COPPER ALLOY
PLATING: PER ES-88 - SEE CHART
 2. SEE CHART FOR REFERENCE DOCUMENTS
 3. PLUG MATES WITH RECEPTACLE ASSEMBLIES: 75545-5000 & 75545-5001
 4. MODULE IS DESIGNED FOR PRESS FIT TO THE PCB
 5. MODULE ASSEMBLY IS RoHS COMPLIANT
 6. GATHERABILITY: ±0.65/.026 X-DIRECTION ±130/.051 Y-DIRECTION
 7. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002
 8. PLATED THRU HOLE (PTH) DIMENSIONS: Ø1.09±0.05/.043±.002 FINISHED PTH (TYP) Ø1.200±0.013/.0472±.0005 DRILL 0.025/.001 COPPER PLATE THICKNESS



CORRECTED HSG GRAPHICS IEC NO: UCP2014-2193 DRAWN: DULLES 2013/11/18 CHKD: BANDURA 2013/11/19 APPR: APATEL 2013/12/10 REV A4	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION						
				mm	INCH	DRAWN BY BANDURA	DATE 2007/01/16	TITLE POWERMASS 80 AMP MODULE, PLUG							
						CHECKED BY MDATA	DATE 2007/01/16								
						APPROVED BY APATEL	DATE	molex SD-75561-200							
			ANGULAR ±1/2°			MATERIAL NO. SEE CHART						DOCUMENT NO. SD-75561-200		SHEET NO. 1 OF 1	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE D						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			